



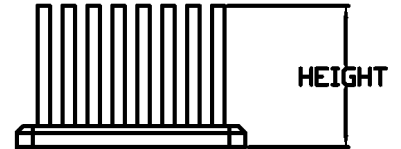
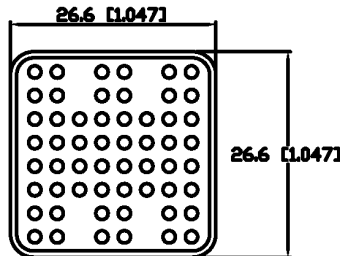
Model : CMBA022727 Series

BGA Heat Sink Specification

For 27x27 Chip set



- 1. Material : Al 6063
- 2. Dimension :
Foot print : 27x27mm
Height : 12,15,18,21,23,28,33 mm
Base (thickness) : 2.6mm



- 3. Finish: Black Anodize
- 4. Chip set package thickness and clip color
3.3+/-0.25mm - Yellow clip
1.7+/-0.25mm - Blue clip
0.8+/-0.25mm - Orange clip
- 5. Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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